

Claims

What is claimed is:

- 5 1. A chip adhesive adhered to a stacked packaging structure between two adjacent chips, and the chip adhesive includes a plurality of stuff particles to keep the chip adhesive with a predetermined thickness.
2. The chip adhesive of claim 1 can further control the thickness through
10 suitably selecting a type of the stuff particle.
3. The chip adhesive of claim 1 can further control the thickness through suitably selecting a quantity of the stuff particle.
- 15 4. A stacked packaging structure utilizing a chip adhesive, comprising:
a stacked packaging structure constituted on an substrate, and the stacked packaging structure has a plurality of chips stacked from bottom to top;
and
a chip adhesive adhered between these two adjacent chips, and the chip
20 adhesive includes a plurality of stuff particles to keep the chips with a predetermined thickness.
5. The stacked packaging structure of claim 4 can further control the thickness through suitably selecting a type and a quantity of the stuff particle.

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